PCN Number:	20230814007.1		PCN Date:	September 18, 2023
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)			
Customer Contact:	Change Management team	Dept:	Quality Services	
Proposed 1st Ship Date:	Dec 18, 2023	Sample requests accepted until:	Oct 18, 2023*	

*Sample requests received after Oct 18, 2023 will not be supported.

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Material	Current	Proposed
Wire type	0.96mil Au	1.0 mil Cu

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties

2) Maximize flexibility within our Assembly/Test production sites.

3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None.

Product Affected:

LMH32401IRGTR	OPA855IDSGT	OPA858IDSGT	
LMH32401IRGTT	OPA856IDSGR	OPA859IDSGR	
OPA855IDSGR	OPA858IDSGR	OPA859IDSGT	

Qualification Report
Approve Date 02-JUNE -2023

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LMH32401IRGTR
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	3/228/0

QBS: Qual By Similarity
Qual Device LMH32401IRGTR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER